



# RF Power Field Effect Transistors

## N-Channel Enhancement-Mode Lateral MOSFETs

Designed for WiMAX base station applications with frequencies up to 2700 MHz. Suitable for WiMAX, WiBro, BWA, and OFDM multicarrier Class AB and Class C amplifier applications.

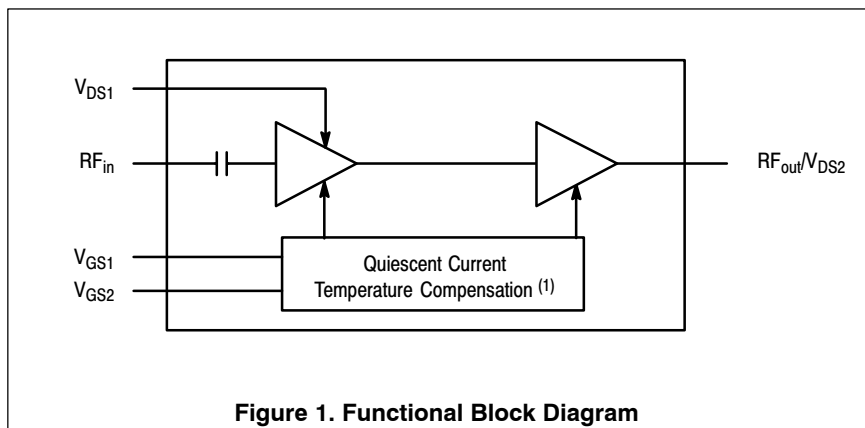
- Typical WiMAX Performance:  $V_{DD} = 28$  Volts,  $I_{DQ1} = 160$  mA,  $I_{DQ2} = 550$  mA,  $P_{out} = 8$  Watts Avg.,  $f = 2700$  MHz, 802.16d, 64 QAM  $3/4$ , 4 bursts, 10 MHz Channel Bandwidth, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF.
  - Power Gain — 26 dB
  - Power Added Efficiency — 17%
  - Device Output Signal PAR — 8.6 dB @ 0.01% Probability on CCDF
  - ACPR @ 8.5 MHz Offset — -49 dBc in 1 MHz Channel Bandwidth

### Driver Applications

- Typical WiMAX Performance:  $V_{DD} = 28$  Volts,  $I_{DQ1} = 160$  mA,  $I_{DQ2} = 550$  mA,  $P_{out} = 4$  Watts Avg.,  $f = 2700$  MHz, 802.16d, 64 QAM  $3/4$ , 4 bursts, 10 MHz Channel Bandwidth, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF.
  - Power Gain — 26 dB
  - Power Added Efficiency — 11%
  - Device Output Signal PAR — 9.2 dB @ 0.01% Probability on CCDF
  - ACPR @ 8.5 MHz Offset — -57 dBc in 1 MHz Channel Bandwidth
- Capable of Handling 10:1 VSWR, @ 32 Vdc, 2600 MHz, 50 Watts CW Output Power
- Stable into a 3:1 VSWR. All Spurs Below -60 dBc @ 1 mW to 80 W CW  $P_{out}$
- $P_{out}$  @ 1 dB Compression Point  $\geq 50$  Watts CW

### Features

- Characterized with Series Equivalent Large-Signal Impedance Parameters and Common Source Parameters
- On-Chip Matching (50 Ohm Input, DC Blocked)
- Integrated Quiescent Current Temperature Compensation with Enable/Disable Function (1)
- Integrated ESD Protection
- Greater Negative Gate-Source Voltage Range for Improved Class C Operation
- 225°C Capable Plastic Package
- RoHS Compliant
- In Tape and Reel. R1 Suffix = 500 Units per 44 mm, 13 inch Reel.

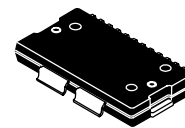
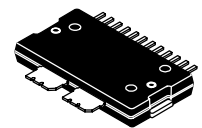


1. Refer to AN1977, Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family and to AN1987, Quiescent Current Control for the RF Integrated Circuit Device Family. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1977 or AN1987.

**MW7IC2750NR1**  
**MW7IC2750GNR1**  
**MW7IC2750NBR1**

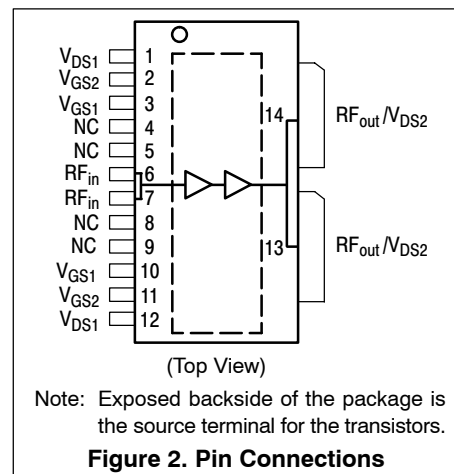
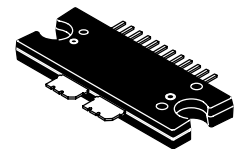
**2700 MHz, 8 W AVG., 28 V**  
**WiMAX**  
**LATERAL N-CHANNEL**  
**RF POWER MOSFETs**

**CASE 1618-02**  
**TO-270 WB-14**  
**PLASTIC**  
**MW7IC2750NR1**



**CASE 1621-02**  
**TO-270 WB-14 GULL**  
**PLASTIC**  
**MW7IC2750GNR1**

**CASE 1617-02**  
**TO-272 WB-14**  
**PLASTIC**  
**MW7IC2750NBR1**



**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-0.5, +65	Vdc
Gate-Source Voltage	$V_{GS}$	-6.0, +10	Vdc
Operating Voltage	$V_{DD}$	32, +0	Vdc
Storage Temperature Range	$T_{stg}$	- 65 to +150	°C
Case Operating Temperature	$T_C$	150	°C
Operating Junction Temperature (1,2)	$T_J$	225	°C
Input Power	$P_{in}$	13	dBm

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value (2,3)	Unit
Thermal Resistance, Junction to Case CW Application (Case Temperature 80°C, $P_{out} = 50$ W CW)	$R_{\theta JC}$	Stage 1, 28 Vdc, $I_{DQ1} = 160$ mA	3.0
		Stage 2, 28 Vdc, $I_{DQ2} = 550$ mA	0.7
Final Application (Case Temperature 70°C, $P_{out} = 8$ W CW)		Stage 1, 28 Vdc, $I_{DQ1} = 160$ mA	2.9
		Stage 2, 28 Vdc, $I_{DQ2} = 550$ mA	0.7
Driver Application (Case Temperature 65°C, $P_{out} = 4$ W CW)		Stage 1, 28 Vdc, $I_{DQ1} = 160$ mA	2.8
		Stage 2, 28 Vdc, $I_{DQ2} = 550$ mA	0.7

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22-A114)	1C (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	III (Minimum)

**Table 4. Moisture Sensitivity Level**

Test Methodology	Rating	Package Peak Temperature	Unit
Per JESD 22-A113, IPC/JEDEC J-STD-020	3	260	°C

**Table 5. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>Stage 1 — Off Characteristics</b>					
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 65$ Vdc, $V_{GS} = 0$ Vdc)	$I_{DSS}$	—	—	10	$\mu\text{A}$ dc
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28$ Vdc, $V_{GS} = 0$ Vdc)	$I_{DSS}$	—	—	1	$\mu\text{A}$ dc
Gate-Source Leakage Current ( $V_{GS} = 5$ Vdc, $V_{DS} = 0$ Vdc)	$I_{GSS}$	—	—	1	$\mu\text{A}$ dc
<b>Stage 1 — On Characteristics</b>					
Gate Threshold Voltage ( $V_{DS} = 10$ Vdc, $I_D = 46$ $\mu\text{A}$ dc)	$V_{GS(th)}$	1	2	3	Vdc
Gate Quiescent Voltage ( $V_{DD} = 28$ Vdc, $I_{DQ1} = 160$ mA, Measured in Functional Test)	$V_{GS(Q)}$	3	3.8	4.5	Vdc
<b>Stage 1 — Dynamic Characteristics (4)</b>					
Input Capacitance ( $V_{DS} = 28$ Vdc, $V_{GS} = 0$ Vdc $\pm 30$ mV(rms)ac @ 1 MHz)	$C_{iss}$	—	550	—	pF

1. Continuous use at maximum temperature will affect MTTF.
2. MTTF calculator available at <http://www.freescale.com/rf>. Select Software & Tools/Development Tools/Calculators to access MTTF calculators by product.
3. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.
4. Part internally matched both on input and output.

(continued)

**Table 5. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>Stage 2 — Off Characteristics</b>					
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 65\text{ Vdc}$ , $V_{GS} = 0\text{ Vdc}$ )	$I_{DSS}$	—	—	10	$\mu\text{Adc}$
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28\text{ Vdc}$ , $V_{GS} = 0\text{ Vdc}$ )	$I_{DSS}$	—	—	1	$\mu\text{Adc}$
Gate-Source Leakage Current ( $V_{GS} = 5\text{ Vdc}$ , $V_{DS} = 0\text{ Vdc}$ )	$I_{GSS}$	—	—	1	$\mu\text{Adc}$

**Stage 2 — On Characteristics**

Gate Threshold Voltage ( $V_{DS} = 10\text{ Vdc}$ , $I_D = 185\ \mu\text{Adc}$ )	$V_{GS(th)}$	1	2	3	Vdc
Gate Quiescent Voltage ( $V_{DD} = 28\text{ Vdc}$ , $I_{DQ2} = 550\text{ mA}$ , Measured in Functional Test)	$V_{GS(Q)}$	2.8	3.6	4.3	Vdc
Drain-Source On-Voltage ( $V_{GS} = 10\text{ Vdc}$ , $I_D = 1\text{ Adc}$ )	$V_{DS(on)}$	0.1	0.12	0.8	Vdc

**Stage 2 — Dynamic Characteristics** <sup>(1)</sup>

Reverse Transfer Capacitance ( $V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$ )	$C_{rss}$	—	0.68	—	pF
Output Capacitance ( $V_{DS} = 28\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$ )	$C_{oss}$	—	220	—	pF

**Functional Tests** (In Freescale Test Fixture, 50 ohm system)  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ1} = 160\text{ mA}$ ,  $I_{DQ2} = 550\text{ mA}$ ,  $P_{out} = 8\text{ W Avg.}$ ,  $f = 2700\text{ MHz}$ , WiMAX Signal, 802.16d, 10 MHz Channel Bandwidth, 64 QAM  $^{3/4}$ , 4 Bursts, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF. ACPR measured in 1 MHz Channel Bandwidth @  $\pm 8.5\text{ MHz}$  Offset.

Power Gain	$G_{ps}$	24	26	31	dB
Power Added Efficiency	PAE	15	17	—	%
Output Peak-to-Average Ratio @ 0.01% Probability on CCDF	PAR	7.8	8.6	—	dB
Adjacent Channel Power Ratio	ACPR	—	-49	-45	dBc
Input Return Loss	IRL	—	-12	-10	dB

**Typical Performances OFDM Signal — 7 MHz Channel Bandwidth** (In Freescale Test Fixture, 50 ohm system)  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ1} = 160\text{ mA}$ ,  $I_{DQ2} = 550\text{ mA}$ ,  $P_{out} = 8\text{ W Avg.}$ ,  $f = 2700\text{ MHz}$ , WiMAX Signal, OFDM Single-Carrier, 7 MHz Channel Bandwidth, 64 QAM  $^{3/4}$ , 4 Bursts, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF.

Mask System Type G @ $P_{out} = 8\text{ W Avg.}$ Point B at 3.5 MHz Offset Point C at 5 MHz Offset Point D at 7.4 MHz Offset Point E at 14 MHz Offset Point F at 17.5 MHz Offset	Mask	—	-27	—	dBc
Relative Constellation Error @ $P_{out} = 8\text{ W Avg.}$ <sup>(2)</sup>	RCE	—	-33	—	dB
Error Vector Magnitude <sup>(2)</sup> (Typical EVM Performance @ $P_{out} = 8\text{ W Avg.}$ with OFDM 802.16d Signal Call)	EVM	—	2.3	—	% rms

**Typical Performances OFDM Signal — 10 MHz Channel Bandwidth** (In Freescale Test Fixture, 50 ohm system)  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ1} = 160\text{ mA}$ ,  $I_{DQ2} = 550\text{ mA}$ ,  $P_{out} = 8\text{ W Avg.}$ ,  $f = 2700\text{ MHz}$ , WiMAX Signal, OFDM Single-Carrier, 10 MHz Channel Bandwidth, 64 QAM  $^{3/4}$ , 4 Bursts, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF.

Relative Constellation Error @ $P_{out} = 8\text{ W Avg.}$ <sup>(1)</sup>	RCE	—	-33	—	dB
Error Vector Magnitude <sup>(1)</sup> (Typical EVM Performance @ $P_{out} = 8\text{ W Avg.}$ with OFDM 802.16d Signal Call)	EVM	—	2.3	—	% rms

1. Part internally matched both on input and output.
2.  $RCE = 20\text{Log}(EVM/100)$

(continued)

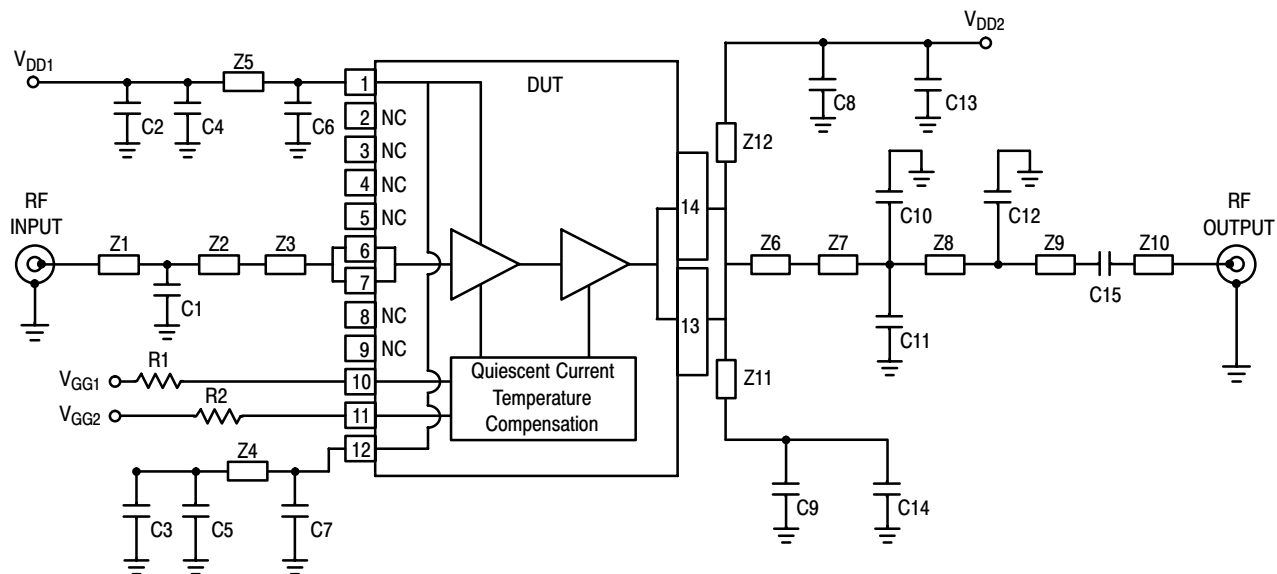
**Table 5. Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>Typical Performances</b> (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$ , $I_{DQ1} = 160\text{ mA}$ , $I_{DQ2} = 550\text{ mA}$ , 2700 MHz Bandwidth					
$P_{out}$ @ 1 dB Compression Point, CW	P1dB	—	55	—	W
IMD Symmetry @ 50 W PEP, $P_{out}$ where IMD Third Order Intermodulation $\cong 30\text{ dBc}$ (Delta IMD Third Order Intermodulation between Upper and Lower Sidebands $> 2\text{ dB}$ )	IMD <sub>sym</sub>	—	60	—	MHz
VBW Resonance Point (IMD Third Order Intermodulation Inflection Point)	VBW <sub>res</sub>	—	50	—	MHz
Gain Flatness in 200 MHz Bandwidth @ $P_{out} = 8\text{ W Avg.}$	$G_F$	—	0.5	—	dB
Average Deviation from Linear Phase in 200 MHz Bandwidth @ $P_{out} = 50\text{ W CW}$	$\Phi$	—	1.1	—	$^\circ$
Average Group Delay @ $P_{out} = 50\text{ W CW}$ , $f = 2600\text{ MHz}$	Delay	—	2.3	—	ns
Part-to-Part Insertion Phase Variation @ $P_{out} = 50\text{ W CW}$ , $f = 2600\text{ MHz}$ , Six Sigma Window	$\Delta\Phi$	—	38.7	—	$^\circ$
Gain Variation over Temperature ( $-30^\circ\text{C}$ to $+85^\circ\text{C}$ )	$\Delta G$	—	0.037	—	dB/ $^\circ\text{C}$
Output Power Variation over Temperature ( $-30^\circ\text{C}$ to $+85^\circ\text{C}$ )	$\Delta P1\text{dB}$	—	0.005	—	dBm/ $^\circ\text{C}$

**Typical Driver Performances** (In Freescale Test Fixture, 50 ohm system)  $V_{DD} = 28\text{ Vdc}$ ,  $I_{DQ1} = 160\text{ mA}$ ,  $I_{DQ2} = 550\text{ mA}$ ,  $P_{out} = 4\text{ W Avg.}$ ,  $f = 2700\text{ MHz}$ , WiMAX Signal, 802.16d, 10 MHz Channel Bandwidth, 64 QAM  $^{3/4}$ , 4 Bursts, Input Signal PAR = 9.5 dB @ 0.01% Probability on CCDF. ACPR measured in 1 MHz Channel Bandwidth @  $\pm 8.5\text{ MHz}$  Offset.

Power Gain	$G_{ps}$	—	26	—	dB
Power Added Efficiency	PAE	—	11	—	%
Output Peak-to-Average Ratio @ 0.01% Probability on CCDF	PAR	—	9.2	—	dB
Adjacent Channel Power Ratio	ACPR	—	-57	—	dBc
Input Return Loss	IRL	—	-13	—	dB
Relative Constellation Error @ $P_{out} = 2.5\text{ W Avg.}$ <sup>(1)</sup>	RCE	—	-39	—	dB

1. RCE =  $20\text{Log}(EVM/100)$

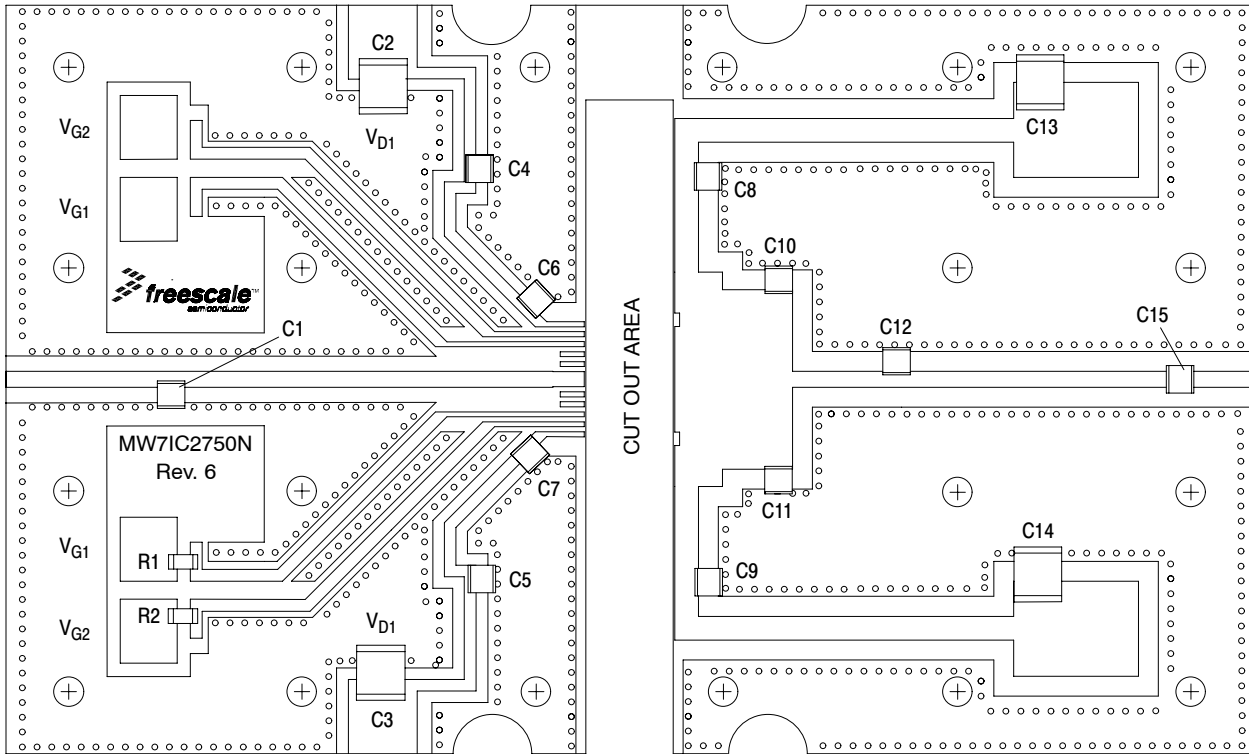


Z1	0.662" x 0.064" Microstrip	Z8	0.417" x 0.064" Microstrip
Z2	1.530" x 0.064" Microstrip	Z9	1.137" x 0.064" Microstrip
Z3	0.126" x 0.060" Microstrip	Z10	0.293" x 0.064" Microstrip
Z4, Z5	0.771" x 0.046" Microstrip	Z11, Z12	0.615" x 0.095" Microstrip
Z6	0.192" x 0.860" Microstrip	PCB	Rogers RO4350B, 0.030", $\epsilon_r = 3.66$
Z7	0.280" x 0.719" Microstrip		

**Figure 3. MW7IC2750NR1(GNR1)(NBR1) Test Circuit Schematic**

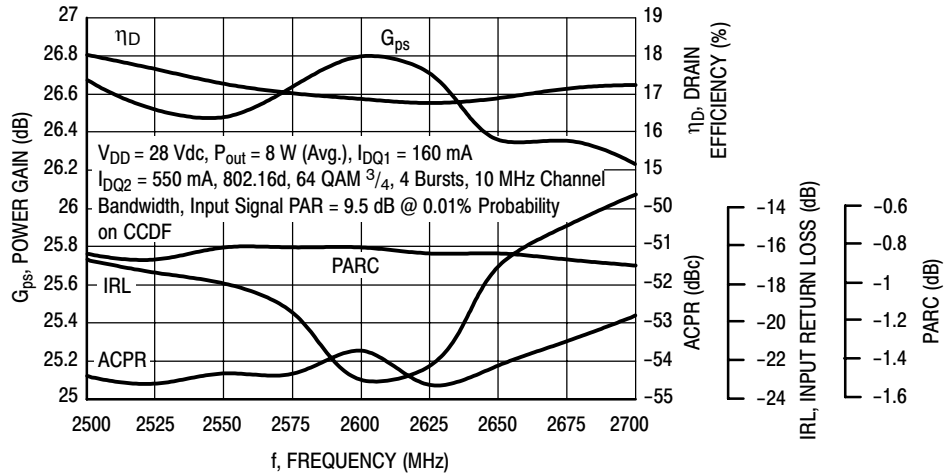
**Table 6. MW7IC2750NR1(GNR1)(NBR1) Test Circuit Component Designations and Values**

Part	Description	Part Number	Manufacturer
C1	0.8 pF Chip Capacitor	ATC100B0R8BT500XT	ATC
C2, C3, C13, C14	10 $\mu$ F, 50 V Chip Capacitors	GRM55DR61H106KA88B	Murata
C4, C5, C8, C9, C15	5.1 pF Chip Capacitors	ATC100B5R1CT500XT	ATC
C6, C7	1 $\mu$ F, 100 V Chip Capacitors	GRM32ER72A105KA01L	Murata
C10, C11	0.2 pF Chip Capacitors	ATC100B0R2BT500XT	ATC
C12	0.5 pF Chip Capacitor	ATC100B0R5BT500XT	ATC
R1, R2	1 K $\Omega$ , 1/4 W Chip Resistors	CRCW12061001FKEA	Vishay

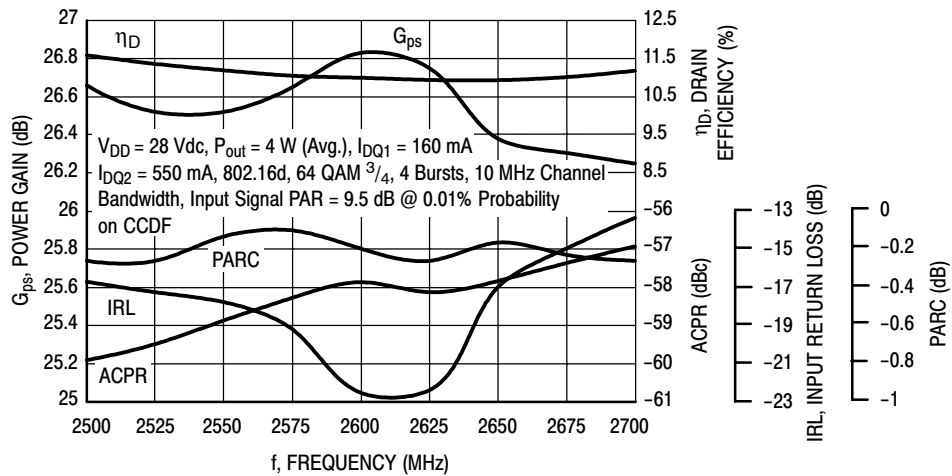


**Figure 4. MW7IC2750NR1(GNR1)(NBR1) Test Circuit Component Layout**

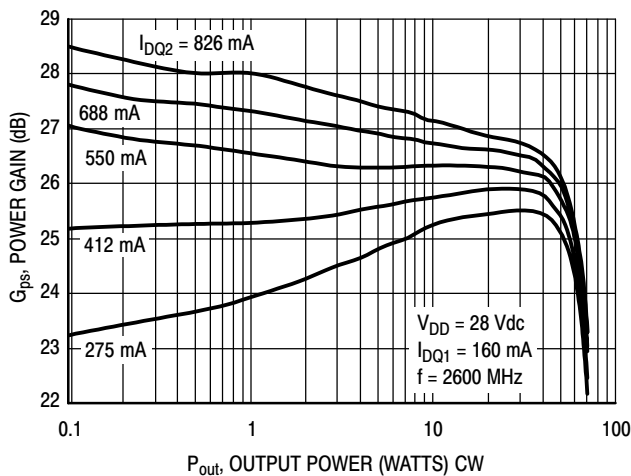
## TYPICAL CHARACTERISTICS



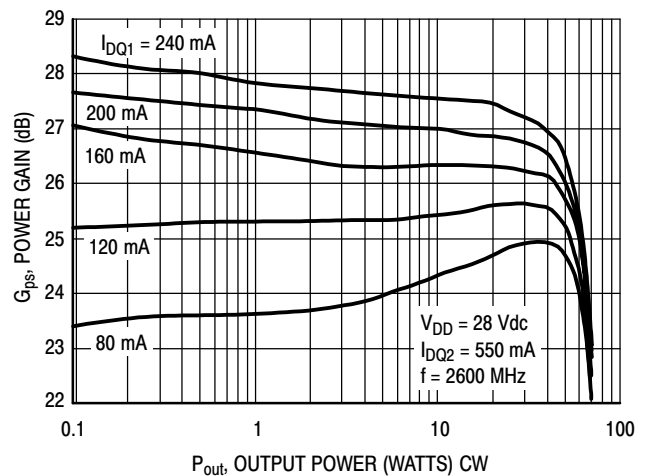
**Figure 5. WiMAX Broadband Performance @  $P_{out} = 8$  Watts Avg.**



**Figure 6. WiMAX Broadband Performance @  $P_{out} = 4$  Watts Avg.**

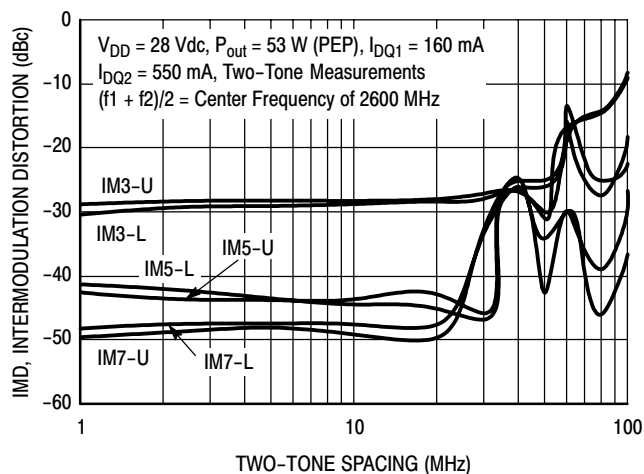


**Figure 7. Power Gain versus Output Power  
@  $I_{DQ1} = 160$  mA**

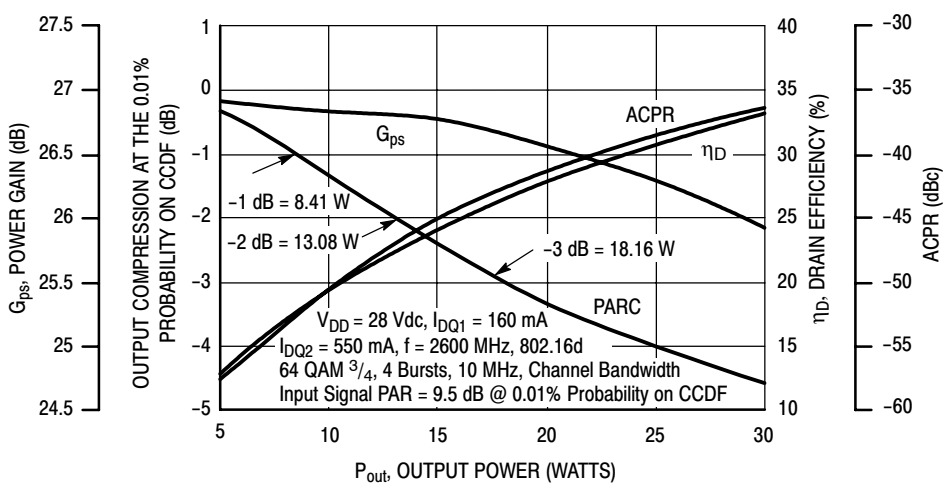


**Figure 8. Power Gain versus Output Power  
@  $I_{DQ2} = 550$  mA**

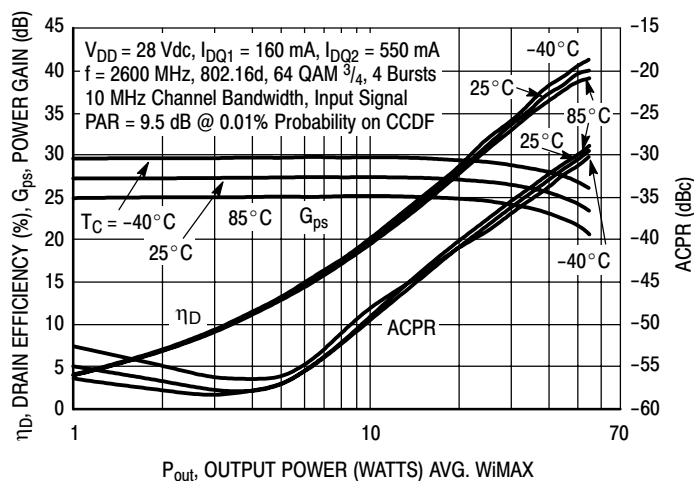
## TYPICAL CHARACTERISTICS



**Figure 9. Intermodulation Distortion Products versus Tone Spacing**



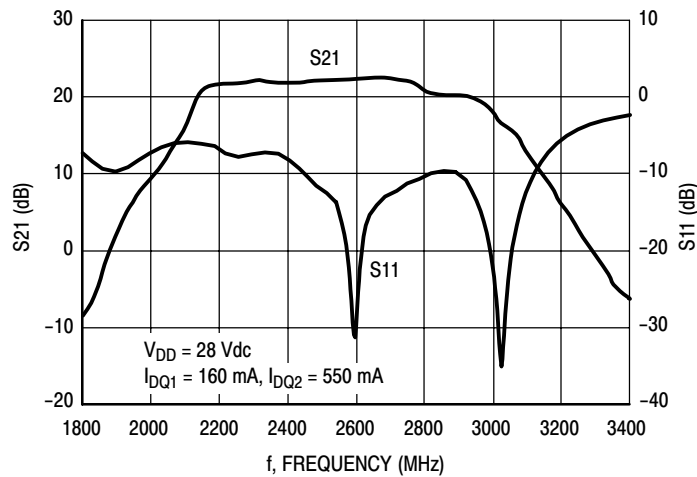
**Figure 10. Output Peak-to-Average Ratio Compression (PARC) versus Output Power**



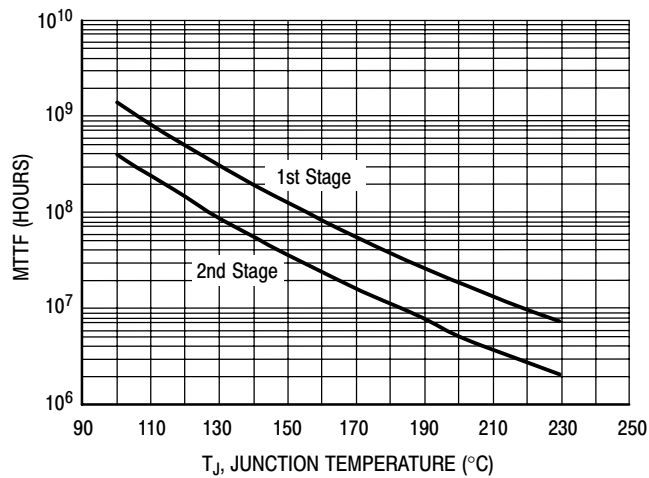
**Figure 11. WiMAX, ACPR, Power Gain and Drain Efficiency versus Output Power**



## TYPICAL CHARACTERISTICS



**Figure 12. Broadband Frequency Response**

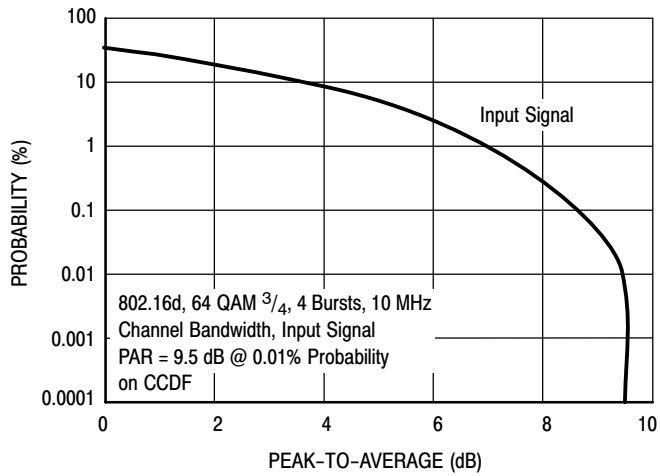


This above graph displays calculated MTTF in hours when the device is operated at  $V_{DD} = 28$  Vdc,  $P_{out} = 8$  W Avg., and PAE = 17%.

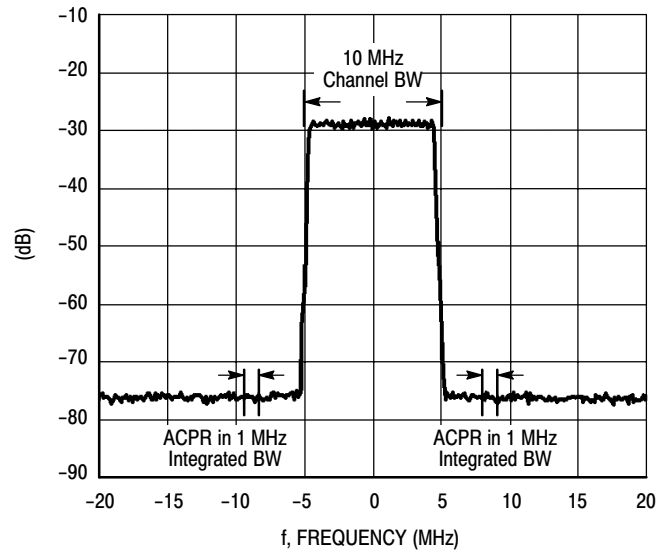
MTTF calculator available at <http://www.freescale.com/rf>. Select Software & Tools/Development Tools/Calculators to access MTTF calculators by product.

**Figure 13. MTTF versus Junction Temperature**

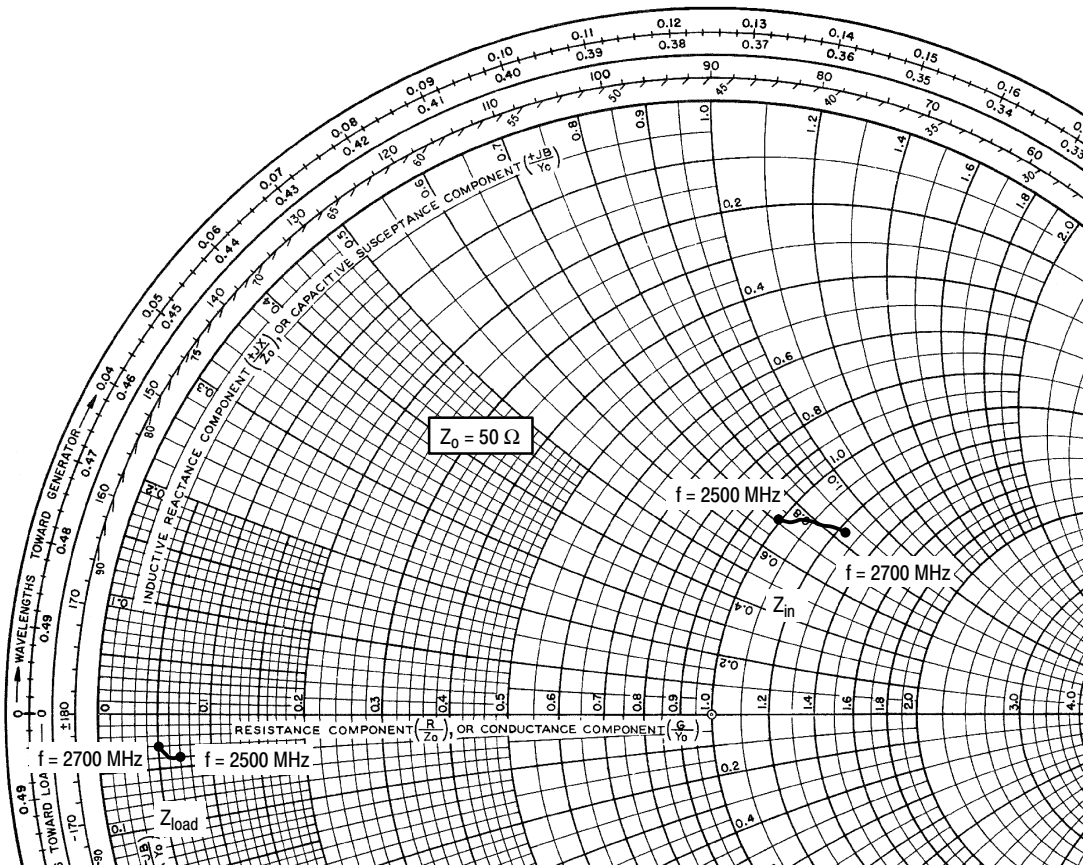
## WIMAX TEST SIGNAL



**Figure 14. OFDM 802.16d Test Signal**



**Figure 15. WiMAX Spectrum Mask Specifications**



$V_{DD} = 28 \text{ Vdc}$ ,  $I_{DQ1} = 160 \text{ mA}$ ,  $I_{DQ2} = 550 \text{ mA}$ ,  $P_{out} = 8 \text{ W Avg.}$

f MHz	$Z_{in}$ $\Omega$	$Z_{load}$ $\Omega$
2500	$49.58 + j35.82$	$3.52 - j1.79$
2525	$50.78 + j36.71$	$3.46 - j1.82$
2550	$52.04 + j37.58$	$3.37 - j1.86$
2575	$53.39 + j38.45$	$3.24 - j1.88$
2600	$54.82 + j39.30$	$3.09 - j1.87$
2625	$56.35 + j40.14$	$2.94 - j1.84$
2650	$57.96 + j40.95$	$2.77 - j1.77$
2675	$59.68 + j41.74$	$2.60 - j1.66$
2700	$61.50 + j42.49$	$2.44 - j1.56$

$Z_{in}$  = Device input impedance as measured from gate to ground.

$Z_{load}$  = Test circuit impedance as measured from drain to ground.

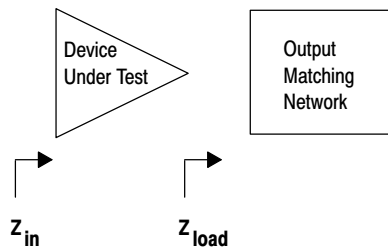


Figure 16. Series Equivalent Source and Load Impedance

**Table 7. Common Source S-Parameters** ( $V_{DD} = 28\text{ V}$ ,  $I_{DQ1} = 160\text{ mA}$ ,  $I_{DQ2} = 550\text{ mA}$ ,  $T_C = 25^\circ\text{C}$ , 50 Ohm System)

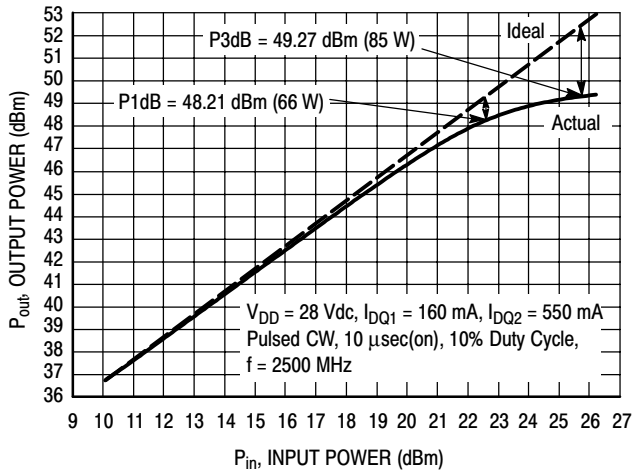
f MHz	S <sub>11</sub>		S <sub>21</sub>		S <sub>12</sub>		S <sub>22</sub>	
	S <sub>11</sub>	∠ φ	S <sub>21</sub>	∠ φ	S <sub>12</sub>	∠ φ	S <sub>22</sub>	∠ φ
1500	0.754	78.5	0.001	-17.9	0.000774	17.4	0.994	174.5
1550	0.734	70.1	0.001	-118.8	0.000326	85.4	0.993	175.3
1600	0.716	61.7	0.003	-116.5	0.000392	58.7	0.998	174.6
1650	0.697	53.4	0.009	-135.3	0.000268	27.8	0.997	173.9
1700	0.677	45.1	0.024	-152.3	0.000211	-33.8	0.996	172.9
1750	0.651	36.6	0.064	-179.9	0.000309	148.0	0.991	171.7
1800	0.619	27.6	0.141	146.0	0.000599	148.7	0.981	170.3
1850	0.578	17.7	0.255	113.0	0.000732	142.6	0.970	169.0
1900	0.527	5.6	0.425	84.8	0.000734	149.1	0.957	167.3
1950	0.462	-9.3	0.701	61.4	0.000911	144.7	0.941	165.6
2000	0.392	-27.8	1.237	39.8	0.00154	174.4	0.924	163.6
2050	0.312	-51.0	2.342	15.9	0.00286	159.0	0.895	160.9
2100	0.218	-74.1	4.772	-11.8	0.00377	142.2	0.843	156.6
2150	0.139	-77.4	11.680	-51.5	0.00588	128.7	0.691	149.4
2200	0.426	-69.8	27.658	-129.7	0.00919	73.9	0.342	-169.4
2250	0.490	-123.5	21.740	150.4	0.00545	38.1	0.800	-166.9
2300	0.416	-146.4	16.087	106.5	0.00314	33.9	0.864	-174.9
2350	0.352	-160.1	13.279	71.6	0.00239	24.9	0.879	-177.0
2400	0.321	-166.6	11.654	41.9	0.00175	33.1	0.891	-177.5
2450	0.274	-173.2	10.543	13.4	0.00197	27.7	0.908	-177.4
2500	0.233	-177.6	9.748	-13.4	0.00181	34.5	0.924	-177.5
2550	0.178	179.0	8.983	-40.5	0.00204	31.5	0.943	-177.7
2600	0.123	-167.7	8.199	-65.8	0.00218	35.6	0.957	-178.0
2650	0.108	-148.8	7.452	-89.9	0.00208	33.2	0.970	-178.7
2700	0.121	-132.6	6.730	-113.1	0.00198	23.8	0.978	-179.6
2750	0.146	-119.9	6.008	-135.3	0.00191	31.0	0.985	179.4
2800	0.184	-119.9	5.323	-156.1	0.00211	23.7	0.987	178.3
2850	0.214	-121.0	4.700	-175.6	0.00159	15.5	0.987	177.3
2900	0.261	-127.6	4.109	166.0	0.00205	14.6	0.985	176.3
2950	0.316	-134.0	3.591	149.0	0.00171	19.2	0.984	175.4
3000	0.372	-141.4	3.130	133.3	0.00103	16.7	0.984	174.5
3050	0.430	-150.2	2.733	118.1	0.00095	26.4	0.984	173.8
3100	0.485	-158.9	2.388	103.6	0.00103	36.9	0.984	173.2
3150	0.534	-166.3	2.091	90.1	0.00108	24.1	0.985	172.7
3200	0.585	-172.7	1.846	77.3	0.00127	47.6	0.984	172.4
3250	0.625	-178.0	1.635	65.2	0.00119	57.1	0.986	172.1
3300	0.657	177.3	1.472	52.9	0.00132	53.2	0.985	171.9
3350	0.686	173.2	1.342	40.8	0.00200	53.8	0.985	171.7

(continued)

**Table 7. Common Source S-Parameters** ( $V_{DD} = 28\text{ V}$ ,  $I_{DQ1} = 160\text{ mA}$ ,  $I_{DQ2} = 550\text{ mA}$ ,  $T_C = 25^\circ\text{C}$ , 50 Ohm System) **(continued)**

f MHz	S <sub>11</sub>		S <sub>21</sub>		S <sub>12</sub>		S <sub>22</sub>	
	S <sub>11</sub>	∠ φ	S <sub>21</sub>	∠ φ	S <sub>12</sub>	∠ φ	S <sub>22</sub>	∠ φ
3400	0.702	169.7	1.243	28.4	0.00230	54.4	0.982	171.3
3450	0.718	166.7	1.193	10.8	0.00211	62.5	0.947	170.1
3500	0.721	164.7	0.937	3.1	0.00233	24.3	0.976	173.0
3550	0.746	162.0	0.914	-7.9	0.00213	51.7	0.981	171.9
3600	0.758	158.9	0.857	-21.4	0.00236	55.6	0.978	171.1

## ALTERNATIVE PEAK TUNE LOAD PULL CHARACTERISTICS

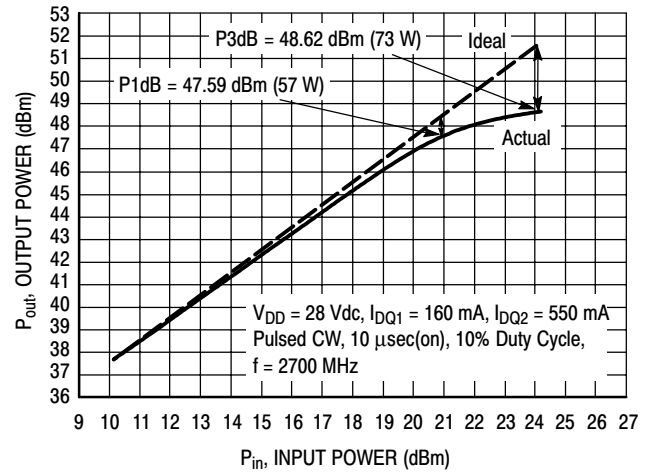


NOTE: Load Pull Test Fixture Tuned for Peak Output Power @ 28 V

Test Impedances per Compression Level

	$Z_{source}$ $\Omega$	$Z_{load}$ $\Omega$
P1dB	28.46 + j5.15	1.67 - j1.53

**Figure 17. Pulsed CW Output Power versus Input Power @ 28 V @ 2500 MHz**



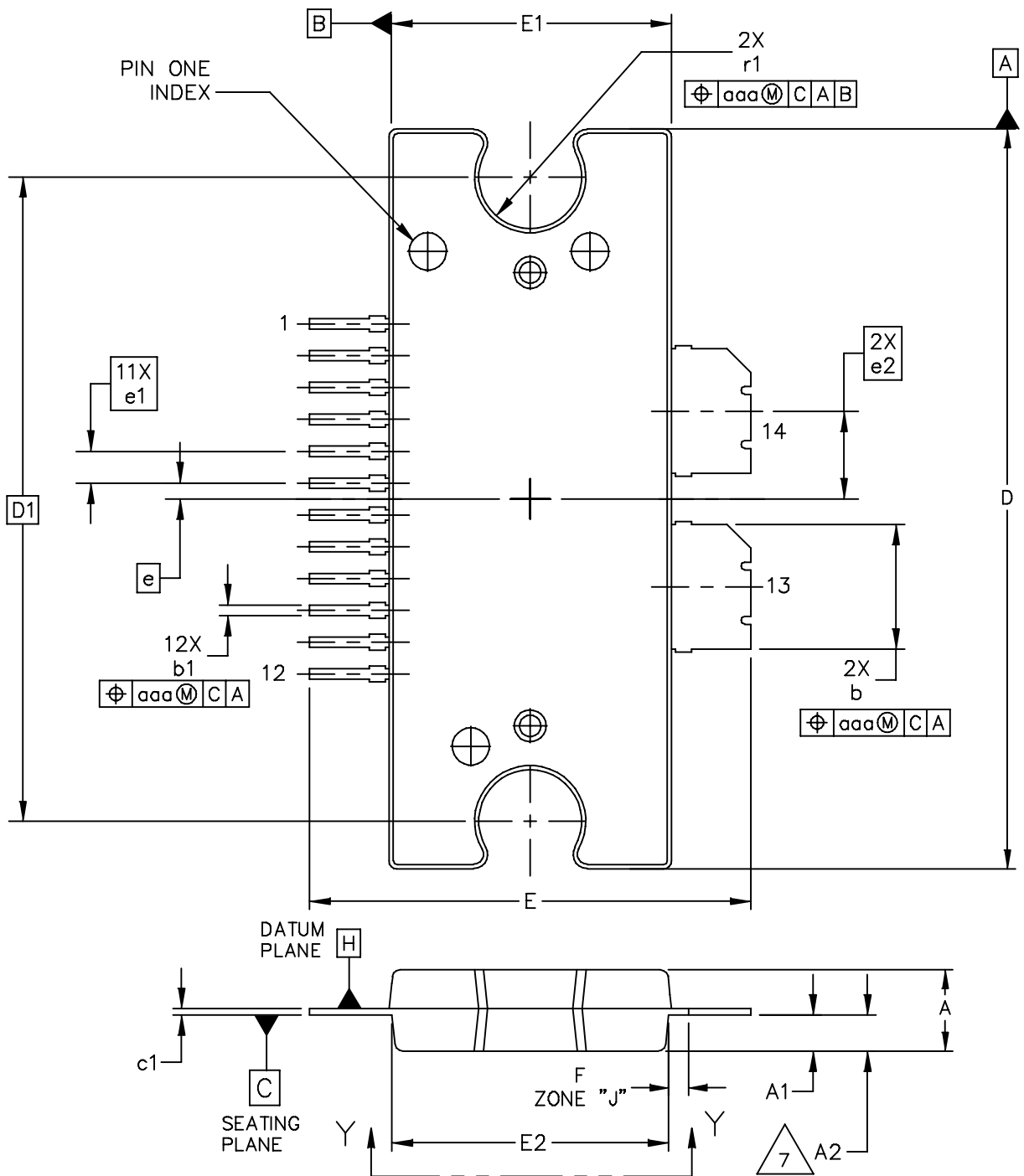
NOTE: Load Pull Test Fixture Tuned for Peak Output Power @ 28 V

Test Impedances per Compression Level

	$Z_{source}$ $\Omega$	$Z_{load}$ $\Omega$
P1dB	36.24 + j1.75	1.19 - j1.29

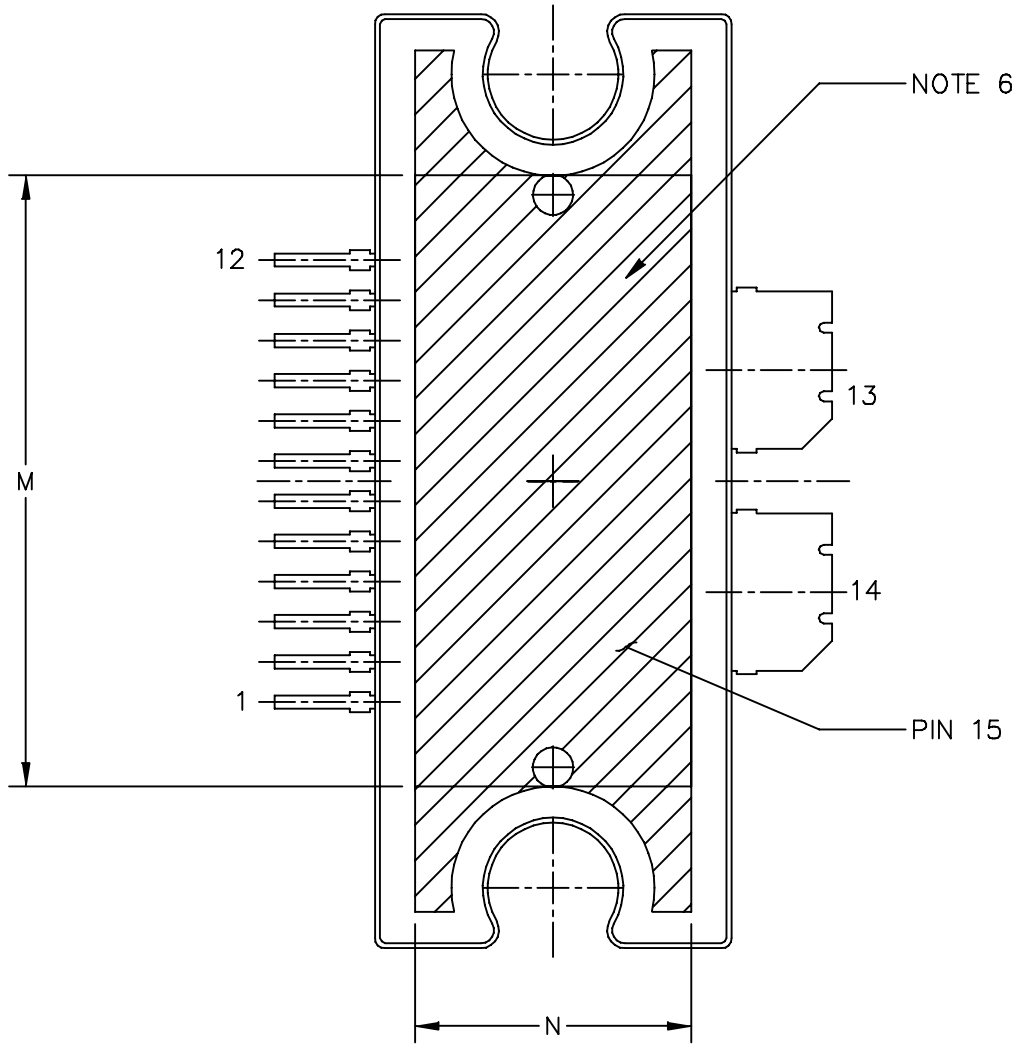
**Figure 18. Pulsed CW Output Power versus Input Power @ 28 V @ 2700 MHz**

PACKAGE DIMENSIONS



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	<p>CASE NUMBER: 1617-02</p>	<p>27 JUN 2007</p>	
	<p>STANDARD: NON-JEDEC</p>		

MW7IC2750NR1 MW7IC2750GNR1 MW7IC2750NBR1



VIEW Y-Y

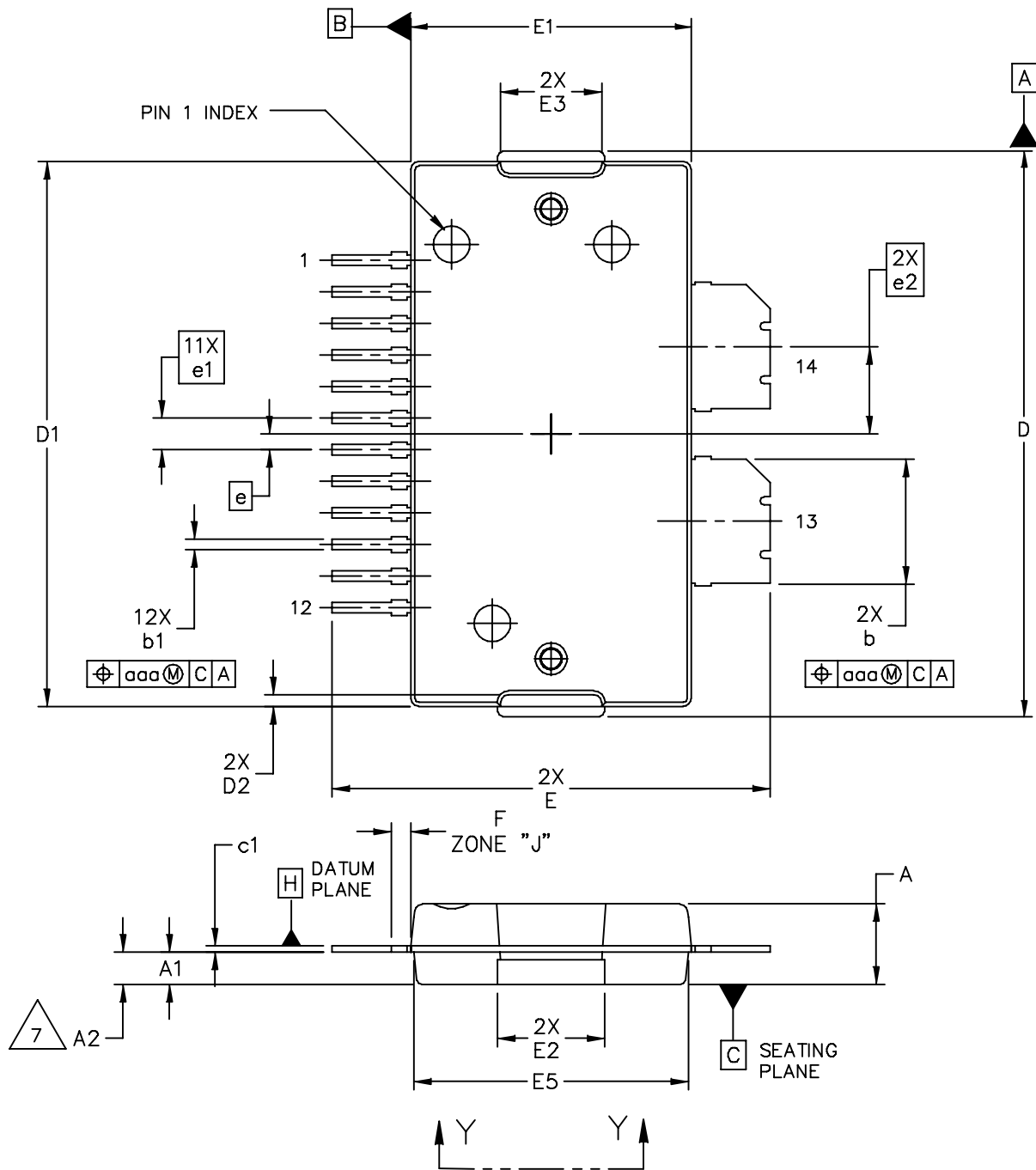
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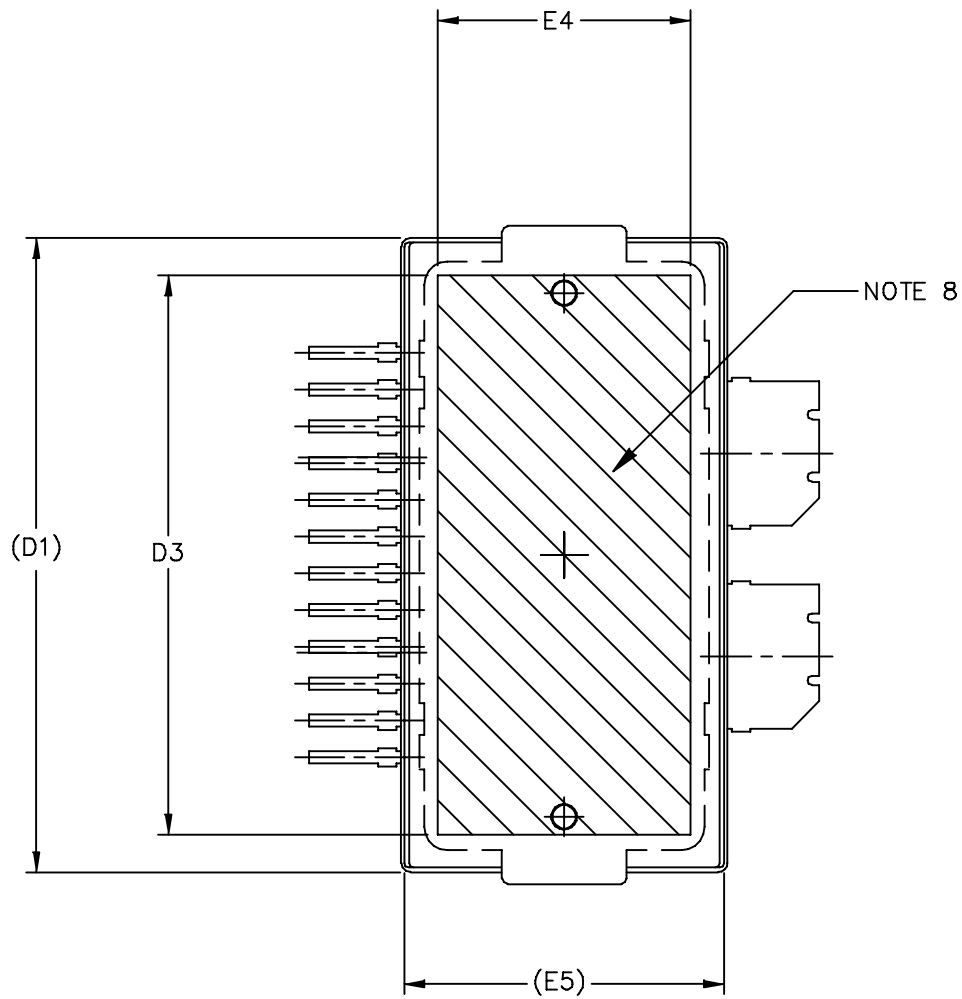
NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 (0.15) PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b" AND "b1" DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 (0.13) TOTAL IN EXCESS OF THE "b" AND "b1" DIMENSIONS AT MAXIMUM MATERIAL CONDITION.
6. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.
7. DIM A2 APPLIES WITHIN ZONE "J" ONLY.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	b	.154	.160	3.91	4.06
A1	.039	.043	0.99	1.09	b1	.010	.016	0.25	0.41
A2	.040	.042	1.02	1.07	c1	.007	.011	0.18	0.28
D	.928	.932	23.57	23.67	e	.020 BSC		0.51 BSC	
D1	.810 BSC		20.57 BSC		e1	.040 BSC		1.02 BSC	
E	.551	.559	14.00	14.20	e2	.1105 BSC		2.807 BSC	
E1	.353	.357	8.97	9.07	r1	.063	.068	1.6	1.73
E2	.346	.350	8.79	8.89	aaa	.004		0.10	
F	.025 BSC		0.64 BSC						
M	.600	----	15.24	----					
N	.270	----	6.86	----					
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VIEW Y-Y

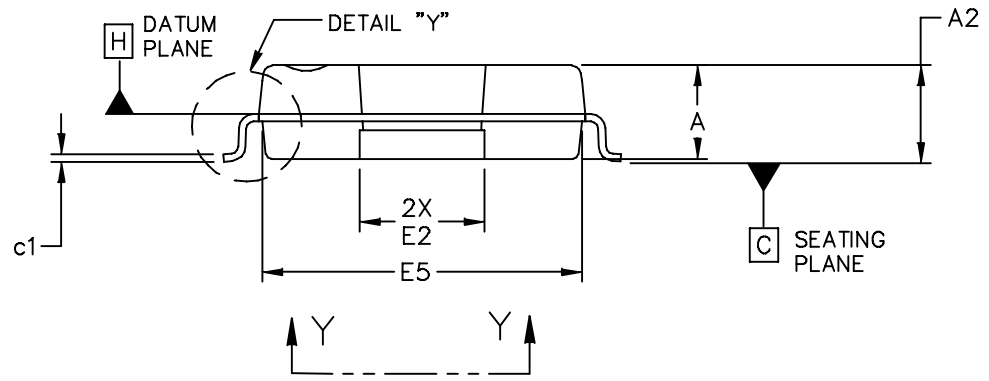
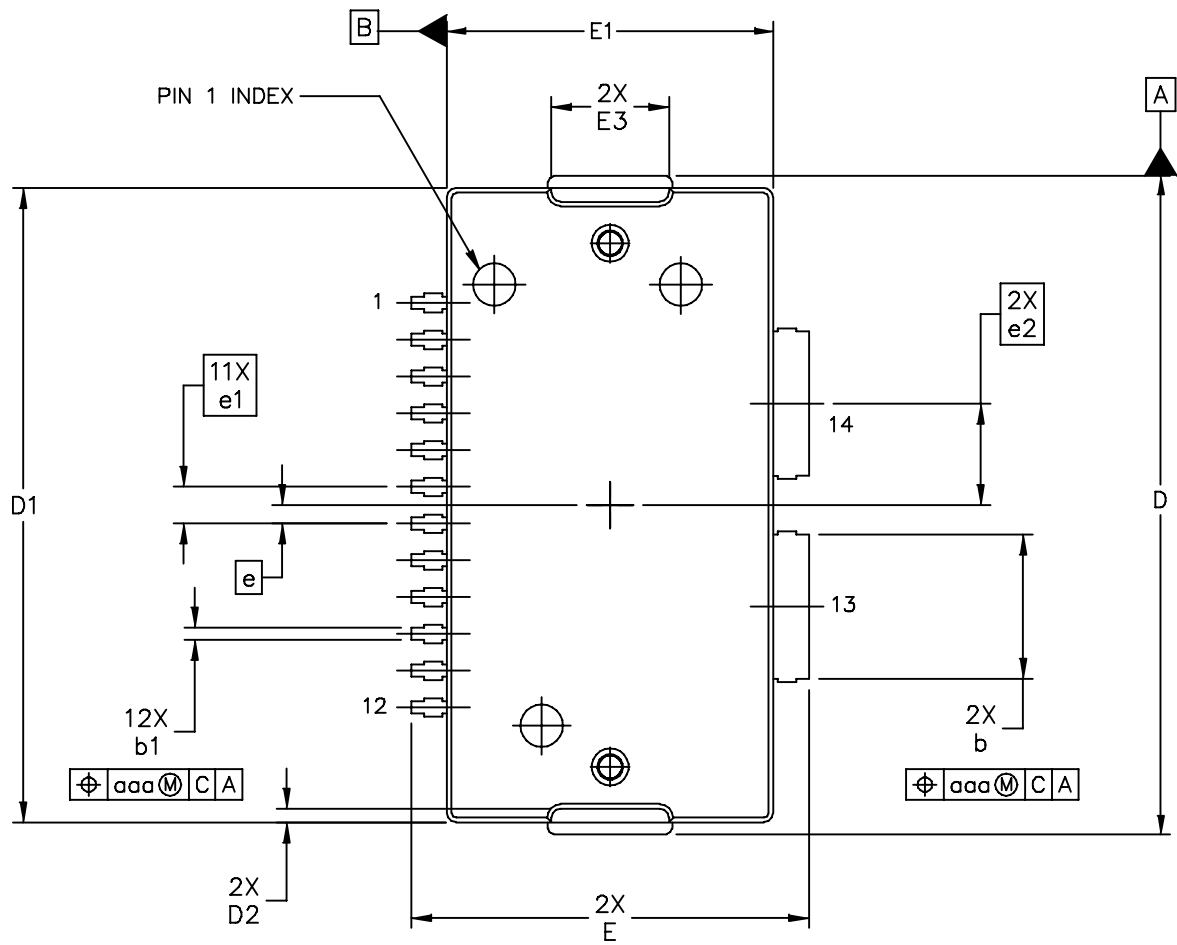
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		STANDARD: NON-JEDEC	

MW7IC2750NR1 MW7IC2750GNR1 MW7IC2750NBR1

NOTES:

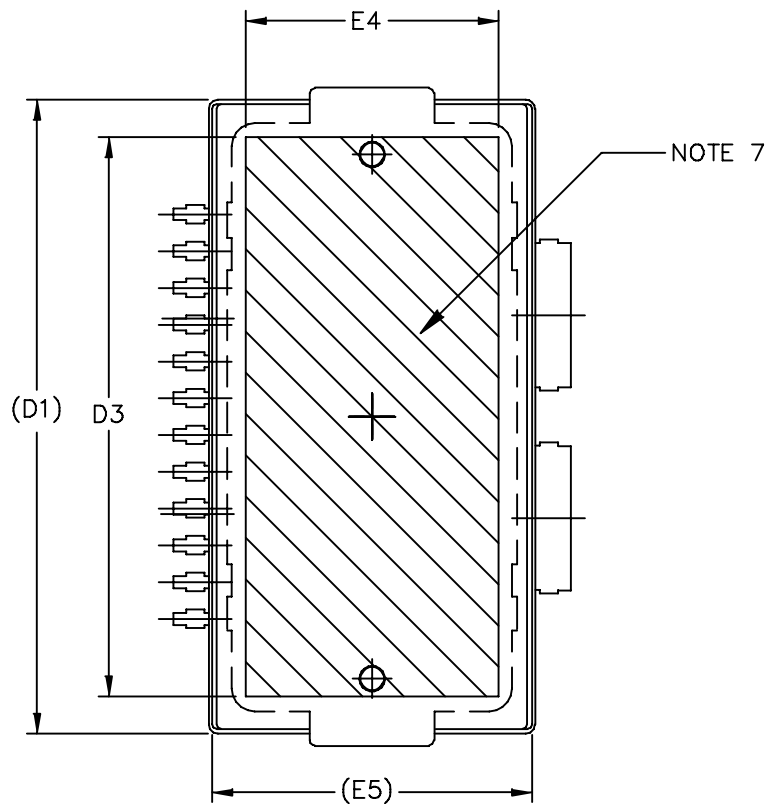
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3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b" AND "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b" AND "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION A2 APPLIES WITHIN ZONE "J" ONLY.
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	F	.025 BSC		0.64 BSC	
A1	.039	.043	0.99	1.09	b	.154	.160	3.91	4.06
A2	.040	.042	1.02	1.07	b1	.010	.016	0.25	0.41
D	.712	.720	18.08	18.29	c1	.007	.011	.18	.28
D1	.688	.692	17.48	17.58	e	.020 BSC		0.51 BSC	
D2	.011	.019	0.28	0.48	e1	.040 BSC		1.02 BSC	
D3	.600	---	15.24	---	e2	.1105 BSC		2.807 BSC	
E	.551	.559	14	14.2					
E1	.353	.357	8.97	9.07	aaa	.004		.10	
E2	.132	.140	3.35	3.56					
E3	.124	.132	3.15	3.35					
E4	.270	---	6.86	---					
E5	.346	.350	8.79	8.89					
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					STANDARD: NON-JEDEC				

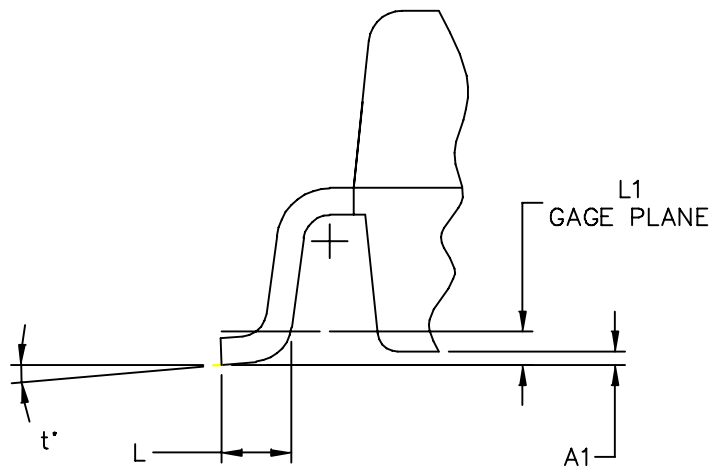


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MW7IC2750NR1 MW7IC2750GNR1 MW7IC2750NBR1



VIEW Y-Y



DETAIL "Y"

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NOTES:

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3. DATUM PLANE -H- IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSIONS "b" AND "b1" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE "b" AND "b1" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.100	.104	2.54	2.64	L	.018	.024	0.46	0.61
A1	.001	.004	0.02	0.10	L1	.010 BSC		0.25 BSC	
A2	.099	.110	2.51	2.79	b	.154	.160	3.91	4.06
D	.712	.720	18.08	18.29	b1	.010	.016	0.25	0.41
D1	.688	.692	17.48	17.58	c1	.007	.011	.18	.28
D2	.011	.019	0.28	0.48	e	.020 BSC		0.51 BSC	
D3	.600	---	15.24	---	e1	.040 BSC		1.02 BSC	
E	.429	.437	10.9	11.1	e2	.1105 BSC		2.807 BSC	
E1	.353	.357	8.97	9.07	t	2'	8'	2'	8'
E2	.132	.140	3.35	3.56					
E3	.124	.132	3.15	3.35	aaa	.004		.10	
E4	.270	---	6.86	---					
E5	.346	.350	8.79	8.89					
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					CASE NUMBER: 1621-02			19 JUN 2007	
					STANDARD: NON-JEDEC				

## PRODUCT DOCUMENTATION

Refer to the following documents to aid your design process.

### Application Notes

- AN1907: Solder Reflow Attach Method for High Power RF Devices in Plastic Packages
- AN1955: Thermal Measurement Methodology of RF Power Amplifiers
- AN1977: Quiescent Current Thermal Tracking Circuit in the RF Integrated Circuit Family
- AN1987: Quiescent Current Control for the RF Integrated Circuit Device Family
- AN3263: Bolt Down Mounting Method for High Power RF Transistors and RFICs in Over-Molded Plastic Packages

### Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

## REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	May 2008	<ul style="list-style-type: none"><li>• Initial Release of Data Sheet</li></ul>



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